ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Par	PC. Bannockl	ourn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities and the declaration entities are an entities and the declaration entities are an entities and the declaration entities are an entities are an entities are an entities and the declaration entities are an entit	on of the su	ibstances v s all lower	vithin the manufact level materials for	urer listed which the	item. Note: manufacture	if the item is an as r has engineering	sembly with low responsibility.	
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg In:					Mfg Informat	ion			
Supplier Information														
Company name* Compa			ompany unique ID			Unique ID Authority				Respo	Response Date*			
nsemi								2025-06-04						
ntact Name Title - Contact				Phone - Contact*				Email	Email - Contact*					
Product-Env-Stewards Product Enviro			iro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repres			sentative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Product Envi			wiro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	M	Manufacturing Site		Weight*	UOM	Unit Type	
	MMSZ4	MMSZ4693T3G ZEN		ZEN SOD123 REG 0.5W 7.5V		2025-06-04		C	CN1		11.525	mg	Each	
Ianufacturing Proccess Informa	tion					·						·		
Terminal Plating / Grid Array Ma	aterial 7	Ferminal Base	lloy J-STD-020 MSL Ratin		L Rating	Peak Process Body Temperatu		emperature	are Max Time at Peak Tempera		ature Num	ber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		C	30	seco	onds 3			
omments														
vel 1 - maximum time at peak temperatu	ire during so	ldering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	toHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.88	mg	Supplier	Silicon (Si)	7440-21-3		0.88	mg
Lead Frame	3.19	mg	В	Nickel (Ni)	7440-02-0		1.158	mg
			Supplier	Iron (Fe)	7439-89-6		1.6014	mg
			Supplier	Copper (Cu)	7440-50-8		0.4306	mg
Mold Compound-Black	6.51	mg	Supplier	Boron zinc hydroxide oxide	138265-88-0		0.1953	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		0.0325	mg
			Supplier	2,4,6-triamino-s-triazincompd.withs- triazine-triol	37640-57-6		0.1953	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		5.208	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0651	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.5208	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.2929	mg
Plating	0.8	mg	Supplier	Tin (Sn)	7440-31-5		0.8	mg
Wire Bond	0.145	mg	Supplier	Palladium (Pd)	7440-05-3		0.0019	mg
			Supplier	Copper (Cu)	7440-50-8		0.1431	mg